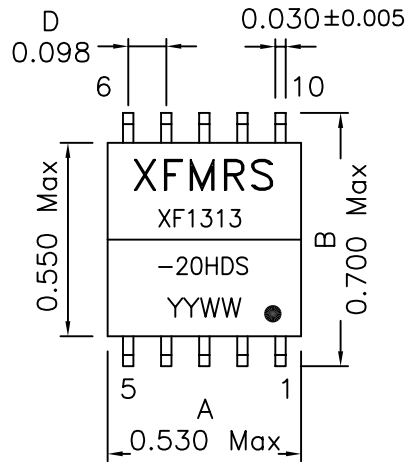
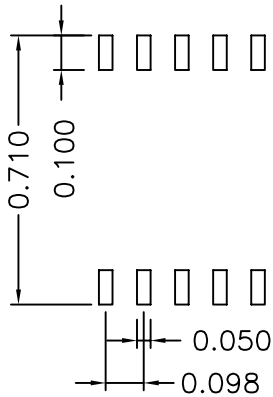
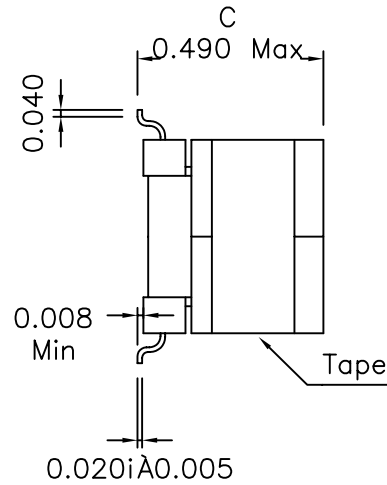


1. Mechanical Dimensions:



CO-PLANARITY: 0.004 Max

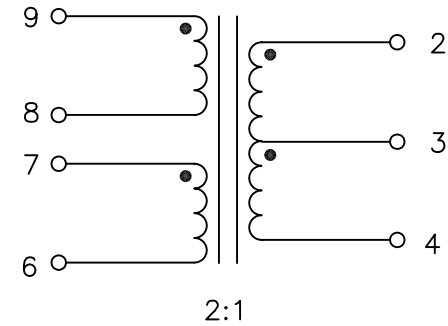


Suggested PCB Layout

Notes:

1. Solderability: Leads shall meet MIL-STD-202, Method 208D for solderability.
2. Flammability: UL94V-0
3. ASTM oxygen index: > 28%
4. Insulation System: Class F 155°C. UL file E151556
5. Operating Temperature Range: -40°C to +85°C
6. Storage Temperature Range: -55°C to +125°C
7. Aqueous wash compatible

2. Schematic:



3. Electrical Specifications:

OCL: (Pins 9-6) 4.0mH ±10% @10KHz, 0.1V Tie 8+7

Leakage L: (Pins 2-4) 8.0uH Max @100KHz, 0.1V
(Short 9,8,7,6)

Longitudinal Balance: 55dB Min @300KHz

THD: 55dB Min @50KHz, 4Vp-p

Return Loss: 16.5dB Min @40KHz - 300KHz

Turns Ratio: (2-4):(9-6) 1CT:2CS ±2% Tie 8+7

DC Res: (Pins 9-8) 3.80 Ohms Max

DC Res.: (Pins 7-6) 3.80 Ohms Max

DC Res.: (Pins 2-4) 3.60 Ohms Max

HYPOT: 2000VAC Chip-Line

Note: Designed to meet UL1950 for supplementary insulation, 250 working volts.

DOC. REV: A/3

XFMRS Inc	Title: HDSL2 TRANSFORMER	
	UNLESS OTHERWISE SPECIFIED TOLERANCES: .xxx ±0.010 Dimensions in INCH	P/N: XF1313-20HDS REV. A
	DWN.	李小锋 Sep-13-01
	CHK.	廖玉坤 Sep-13-01
	APP.	Joe Huff Sep-13-01